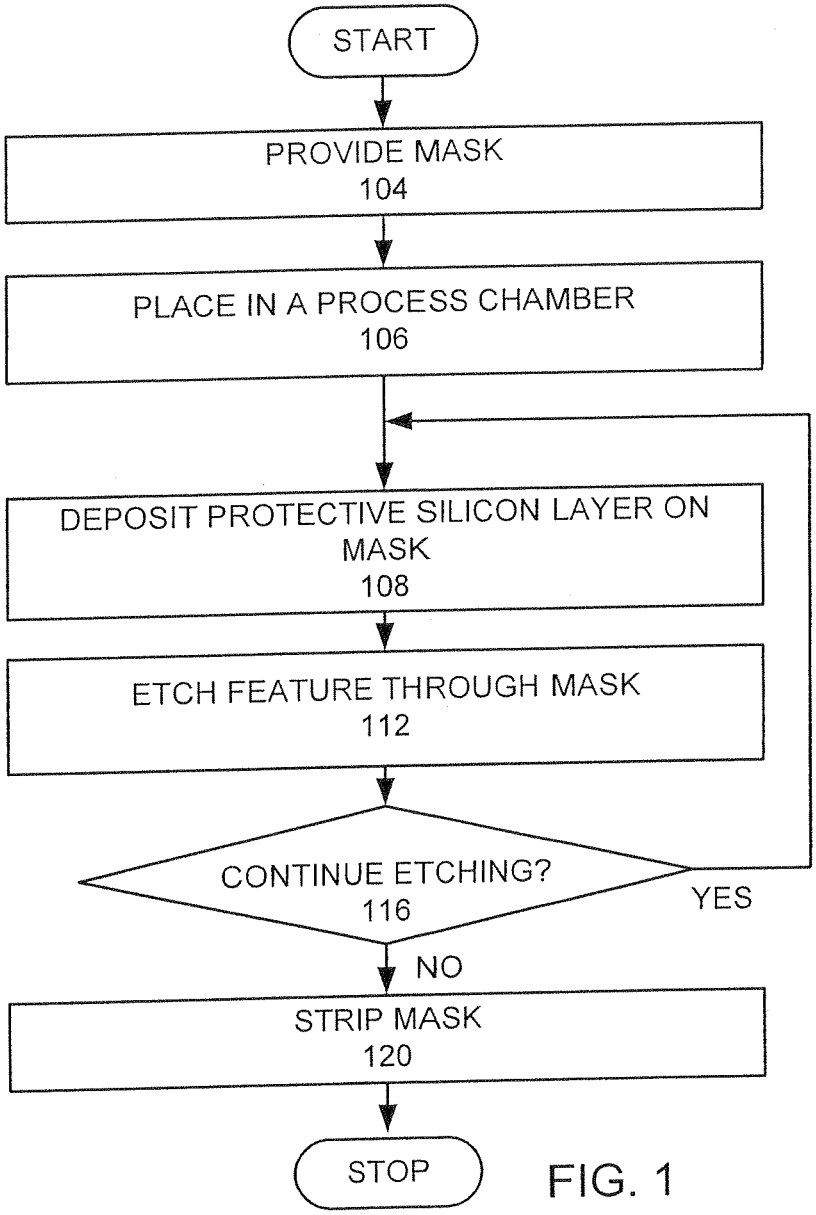

START
PROVIDE MASK
104
PLACE IN A PROCESS CHAMBER
106
DEPOSIT PROTECTIVE SILICON LAYER ON MASK
108
ETCH FEATURE THROUGH MASK
112
CONTINUE ETCHING?
116
YES
NO
STRIP MASK
120
STOP

FIG. 1

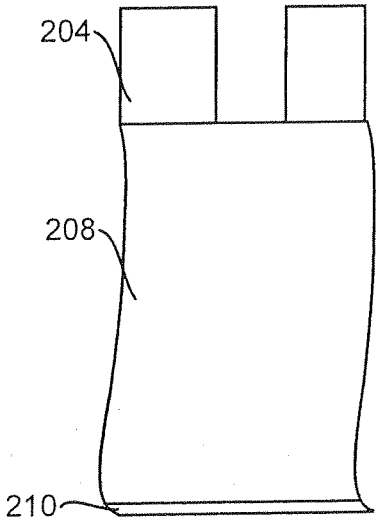


FIG. 2A

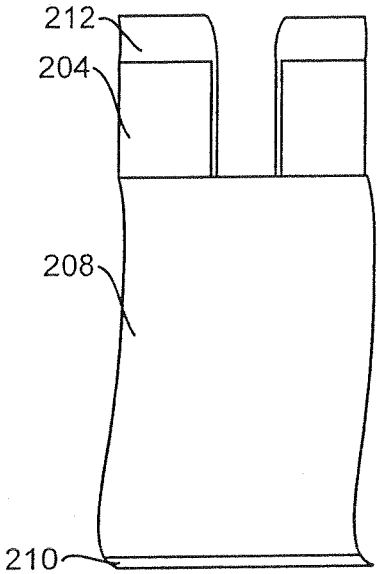


FIG. 2B

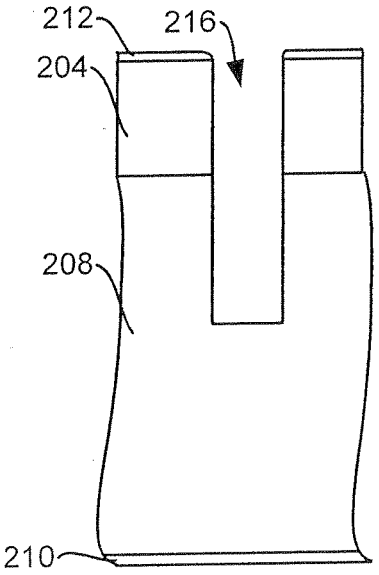


FIG. 2C

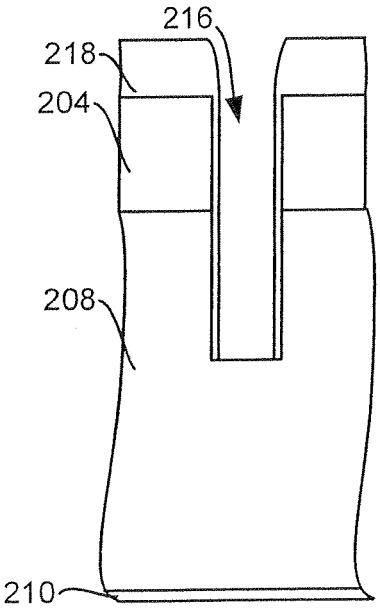


FIG. 2D

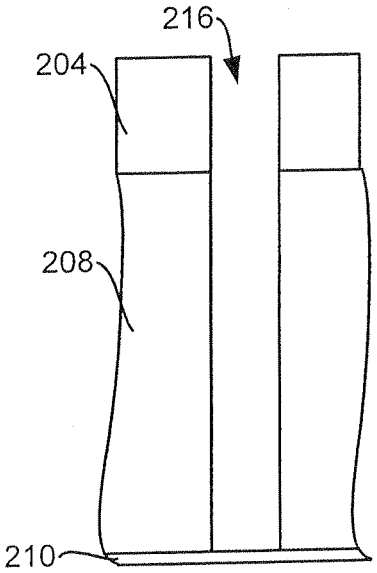


FIG. 2E

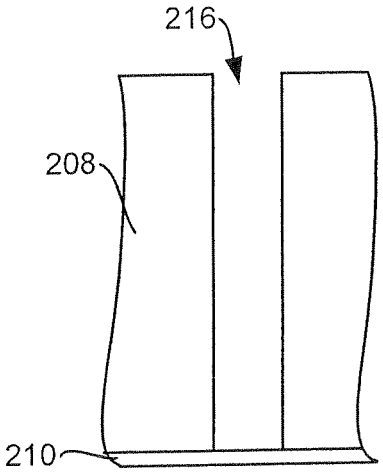


FIG. 2F

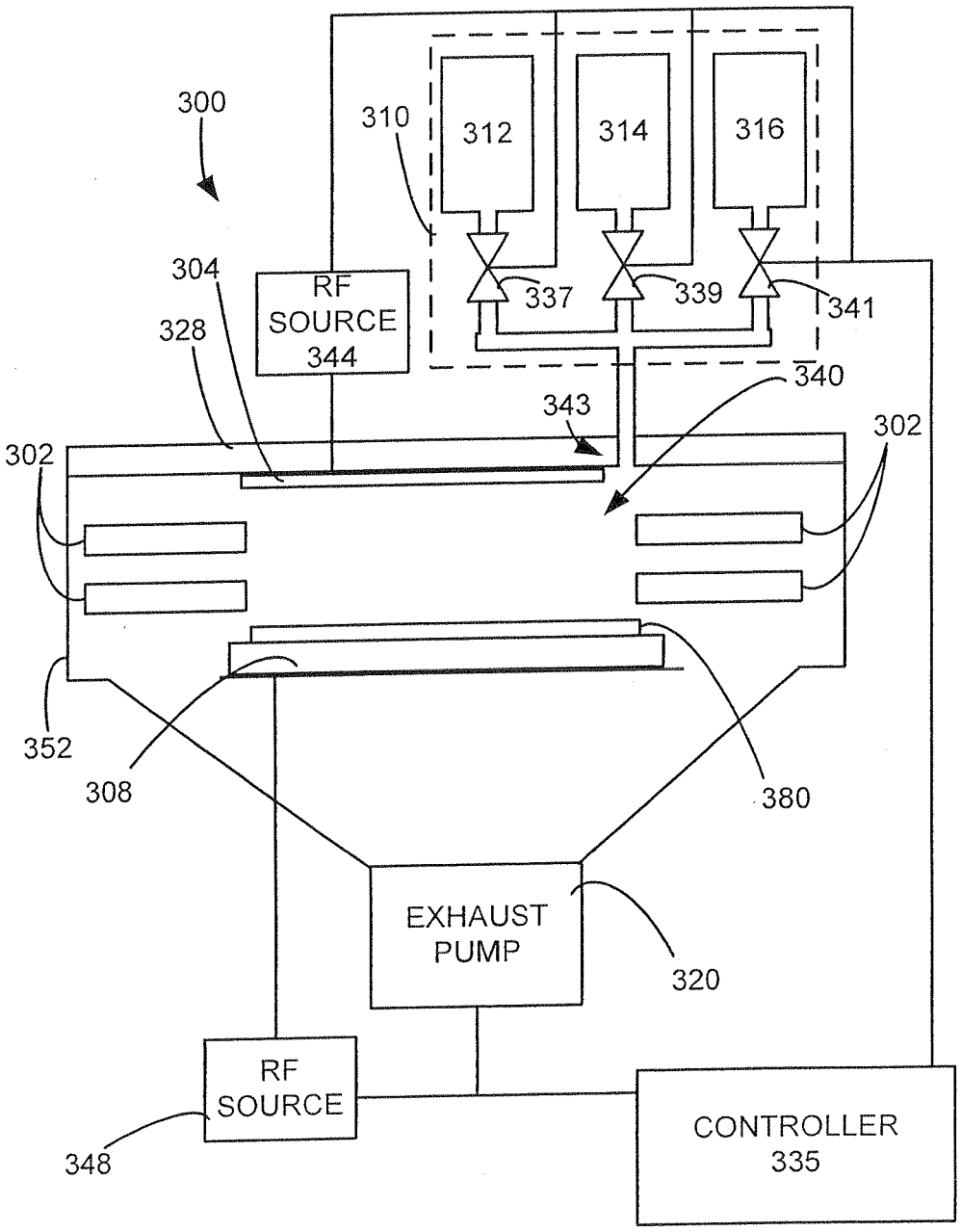

300
310
312
314
316
304
RF
SOURCE
344
337
339
341
328
340
343
302
302
352
308
380
EXHAUST
PUMP
320
RF
SOURCE
348
CONTROLLER
335

FIG. 3

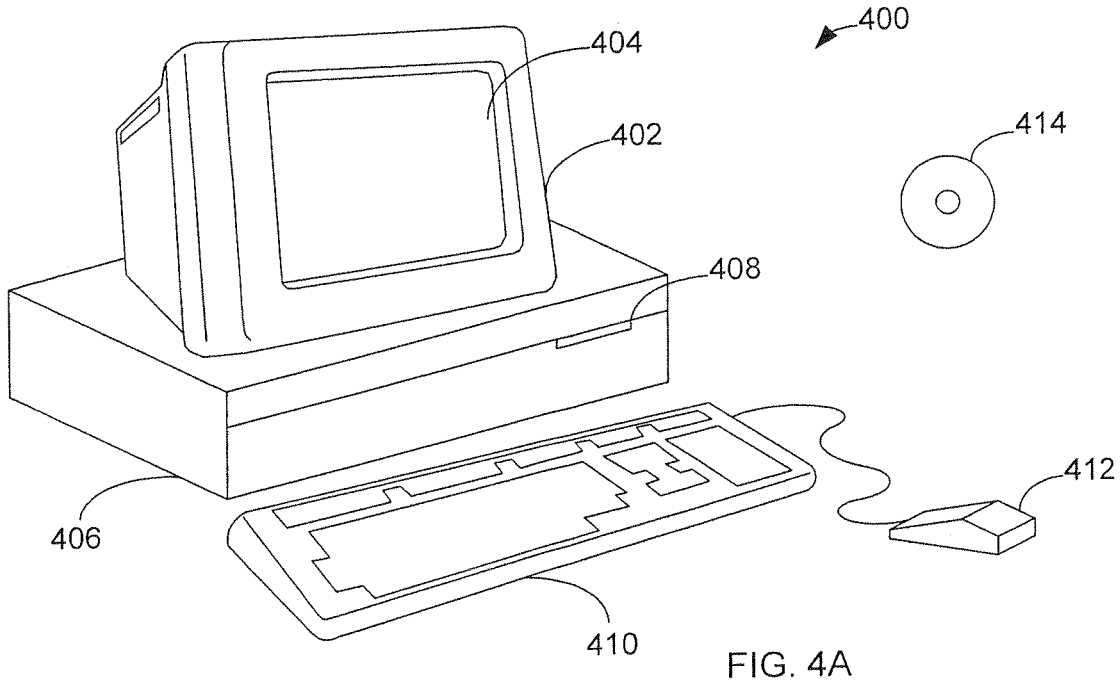

400
404
402
414
408
412
406
410

FIG. 4A

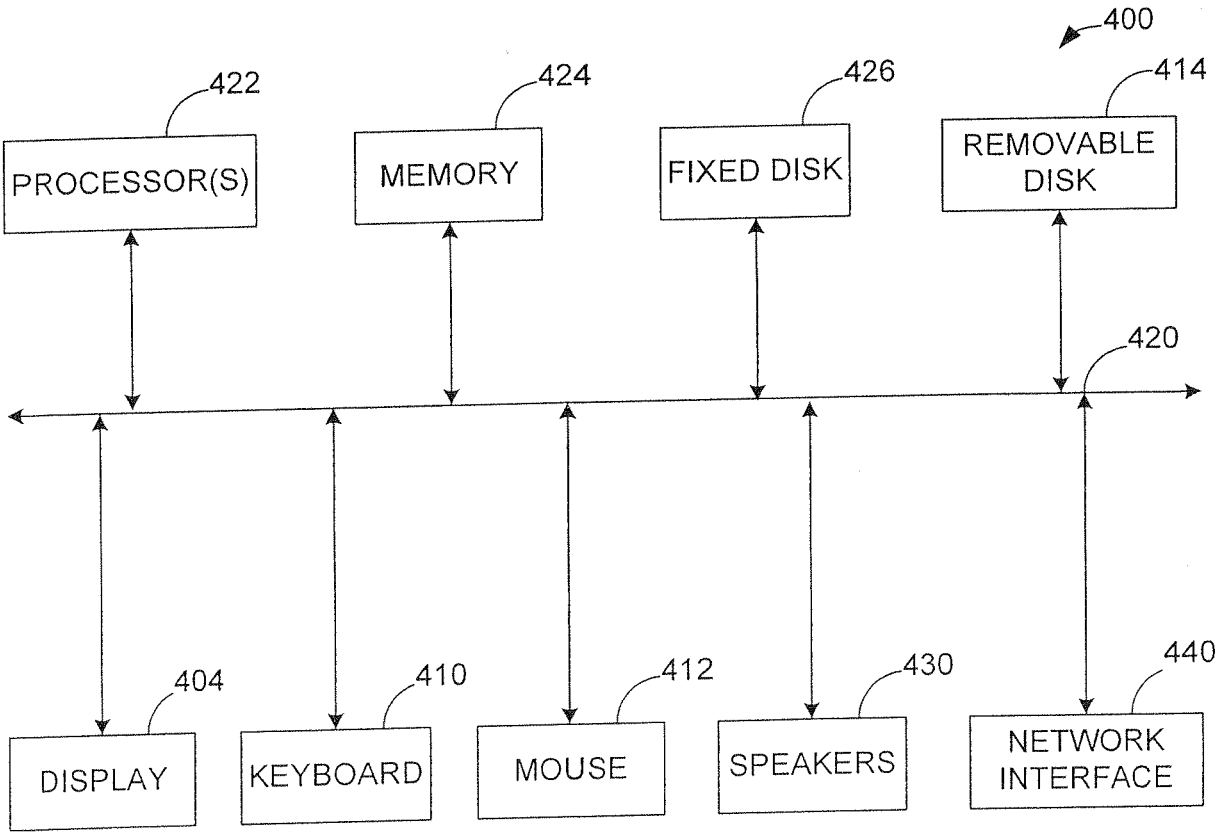

400
422
424
426
414
PROCESSOR(S)
MEMORY
FIXED DISK
REMOVABLE DISK
420
404
410
412
430
440
DISPLAY
KEYBOARD
MOUSE
SPEAKERS
NETWORK INTERFACE

FIG. 4B

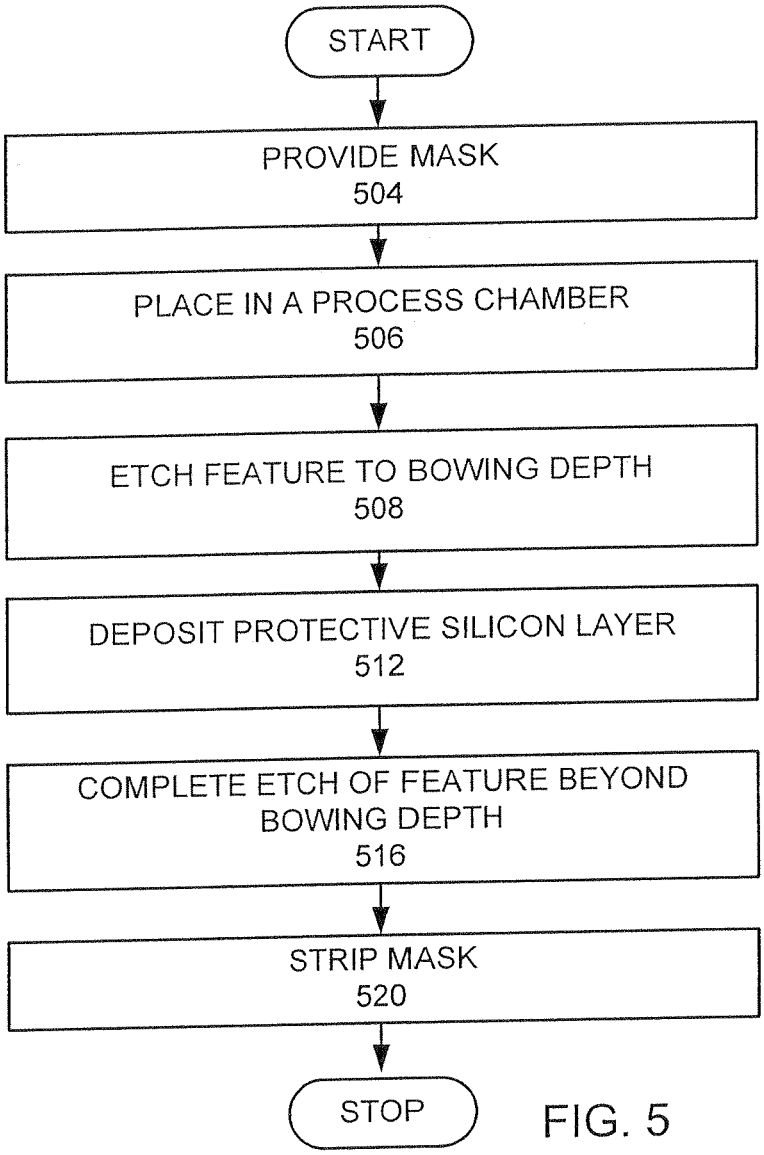

START
PROVIDE MASK
504
PLACE IN A PROCESS CHAMBER
506
ETCH FEATURE TO BOWING DEPTH
508
DEPOSIT PROTECTIVE SILICON LAYER
512
COMPLETE ETCH OF FEATURE BEYOND BOWING DEPTH
516
STRIP MASK
520
STOP

FIG. 5

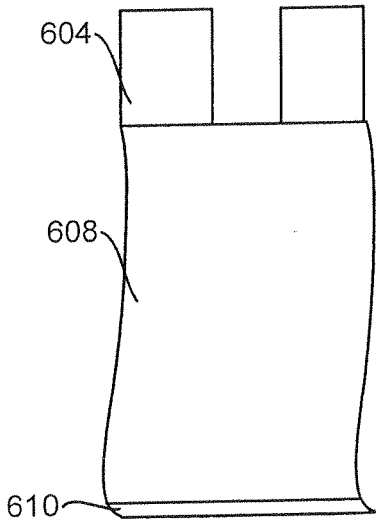


FIG. 6A

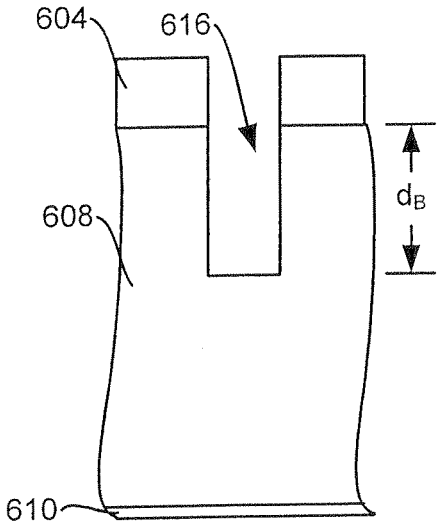


FIG. 6B

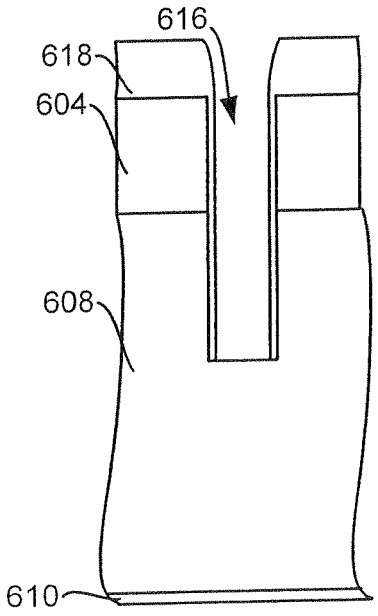


FIG. 6C

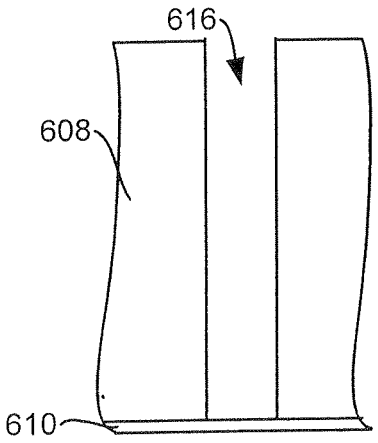


FIG. 6D

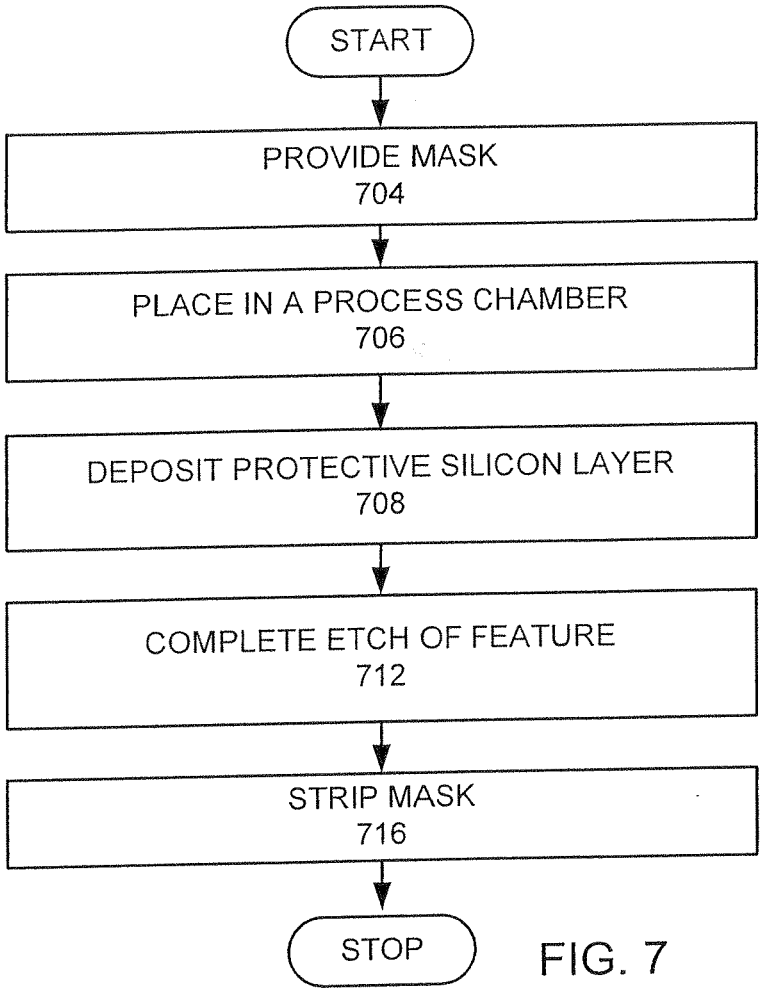

START
PROVIDE MASK
704
PLACE IN A PROCESS CHAMBER
706
DEPOSIT PROTECTIVE SILICON LAYER
708
COMPLETE ETCH OF FEATURE
712
STRIP MASK
716
STOP

FIG. 7

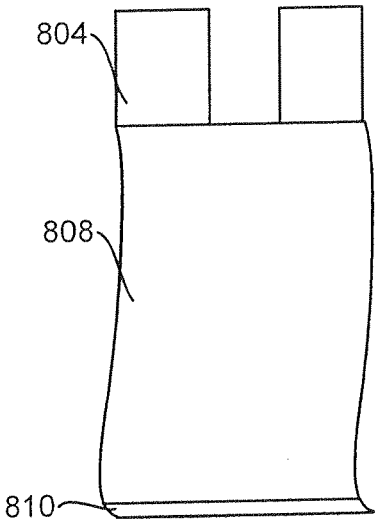


FIG. 8A

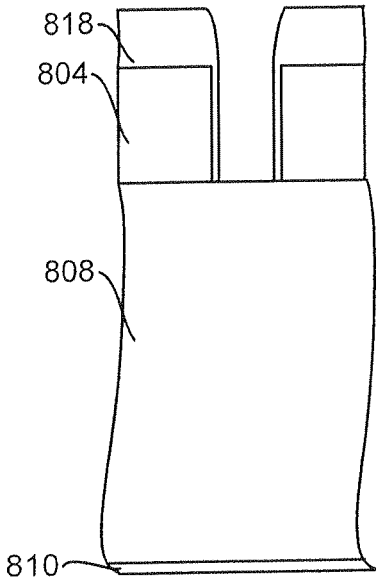


FIG. 8B

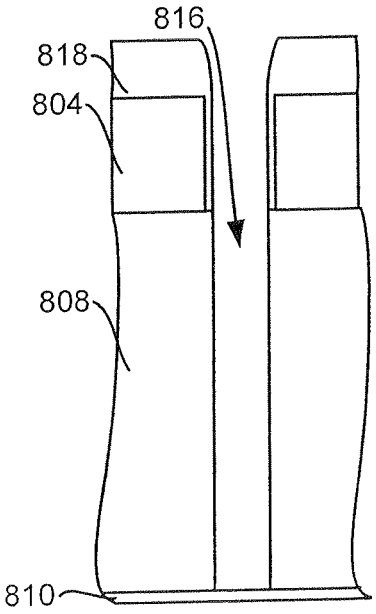


FIG. 8C

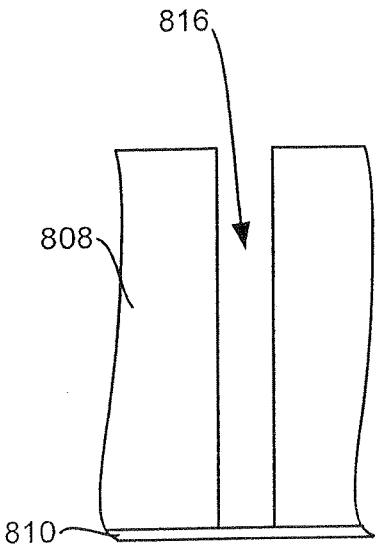


FIG. 8D

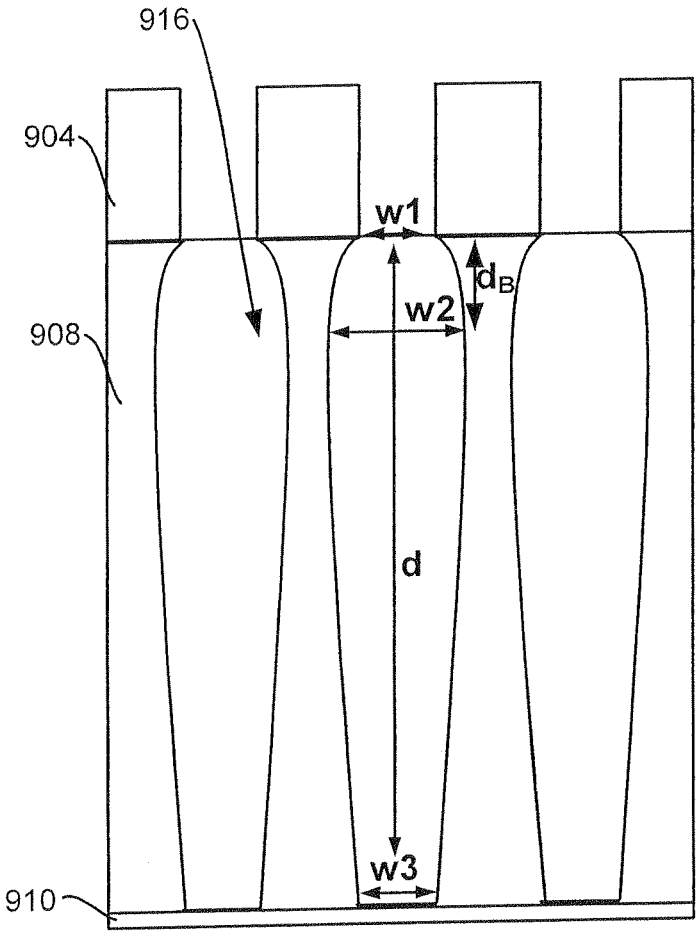


FIG. 9
(PRIOR ART)

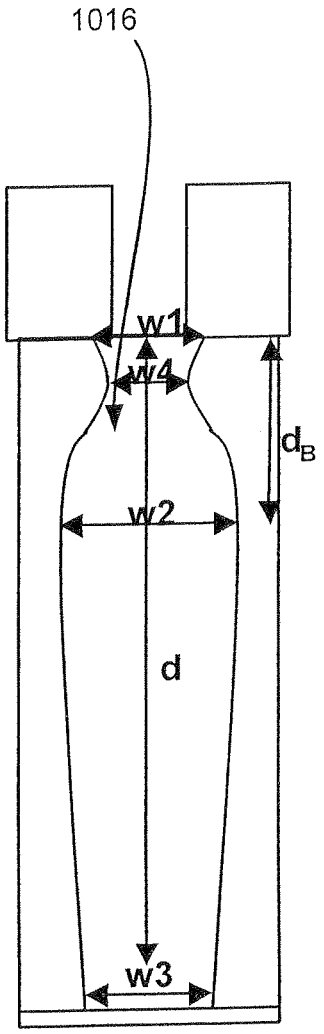


FIG. 10
(PRIOR ART)

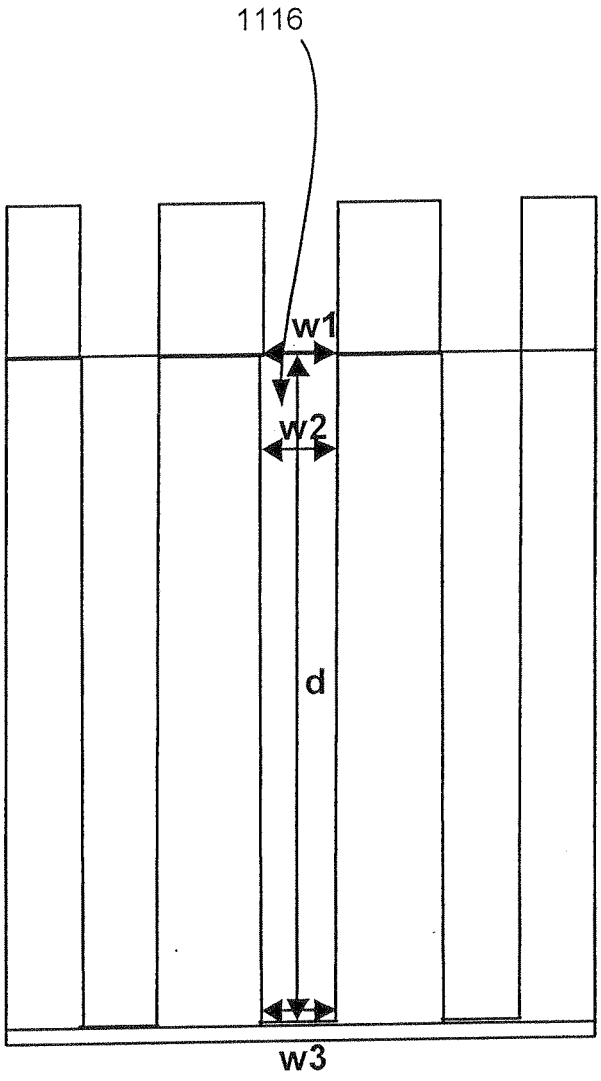


FIG. 11